

Data Sheet

Description

The SJPX-F2 is a fast recovery diode of 200 V / 1.5 A. The maximum $t_{\rm rr}$ of 30 ns is realized by optimizing a life-time control.

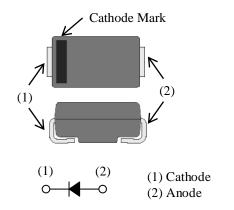
Features

• V _{RM}	200 V
• I _{F(AV)}	1.5 A
	0.98 V
• t _{rr1}	30 ns

- Bare Lead Frame: Pb-free (RoHS Compliant)
- Flammability: Equivalent to UL94V-0
- Suitable for High Reliability and Automotive Requirement.

Package

SJP



Not to scale

Applications

- White Goods
- Audiovisual Equipment
- Lighting Equipment
- Industrial Electronic Equipment (Communication Equipment and Factory Automation)
- Secondary-side Rectifier Diode (Flyback Converter, LLC Converter, etc.)
- Freewheel Diode (Offline Buck Converter, Offline Buck-boost Converter, etc.)

Absolute Maximum Ratings

Unless otherwise specified, $T_A = 25$ °C.

Parameter	Symbol	Conditions	Rating	Unit
Nonrepetitive Peak Reverse Voltage	V _{RSM}		200	V
Repetitive Peak Reverse Voltage	V_{RM}		200	V
Average Forward Current	I _{F(AV)}	See Figure 2 and Figure 3	1.5	A
Surge Forward Current	I_{FSM}	Half cycle sine wave, positive side, 10 ms, 1 shot	30	A
I ² t Limiting Value	I ² t	$1 \text{ ms} \le t \le 10 \text{ ms}$	4.5	A^2s
Junction Temperature	T_{J}		-40 to 150	°C
Storage Temperature	T_{STG}		-40 to 150	°C

Electrical Characteristics

Unless otherwise specified, $T_A = 25$ °C.

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Forward Voltage Drop	V_{F}	$T_J = 25 ^{\circ}\text{C}, I_F = 1.5 \text{A}$	_	_	0.98	V
		$T_J = 100 ^{\circ}\text{C}, I_F = 1.5 \text{A}$	_	0.89	_	V
Reverse Leakage Current	I_R	$V_R = V_{RM}$	_	_	10	μΑ
Reverse Leakage Current under High Temperature	$H \cdot I_R$	$V_R = V_{RM}$, $T_J = 150 ^{\circ}C$	_		2	mA
D. D. Ti	t _{rr1}	$I_F = I_{RP} = 100 \text{ mA},$ 90% recovery point, $T_J = 25 \text{ °C}$	_	_	30	ns
Reverse Recovery Time	Recovery Time t _{rr2}		_	_	25	ns
Thermal Resistance (1)	R _{th(J-L)}		_	_	20	°C/W

Mechanical Characteristics

Parameter	Conditions	Min.	Тур.	Max.	Unit
Package Weight		_	0.072		g

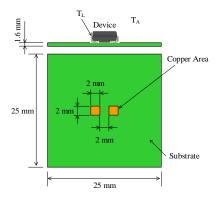
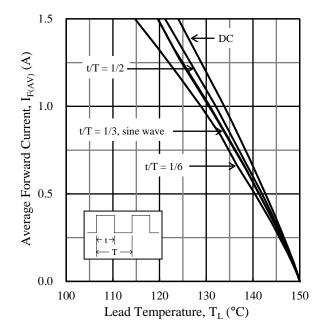


Figure 1. Lead Temperature Measurement Conditions

 $^{^{(1)}}$ $R_{th (J-L)}$ is thermal resistance between junction and case. Lead temperature (T_L) is measured near the root of pin (see Figure 1).

Derating Curves



 $\label{eq:Figure 2.} Figure \ 2. \quad Typical \ Characteristics: \ I_{F(AV)} \ vs. \ T_L \\ (T_J = 150 \ ^{\circ}C, \ V_R = 0 \ V)$

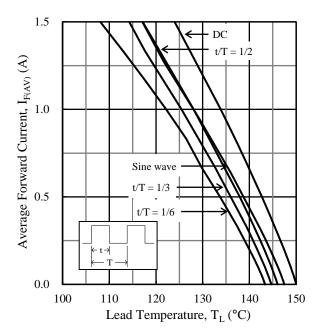


Figure 3. Typical Characteristics: $I_{F(AV)}$ vs. T_L $(T_J=150~^{\circ}C,~V_R=200~V)$

Characteristic Curves

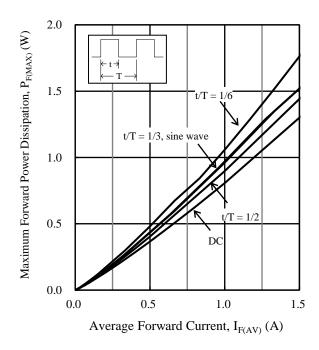


Figure 4. $P_{F(MAX)}$ vs. $I_{F(AV)}$ ($T_J = 150$ °C)

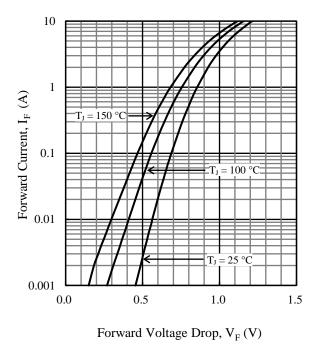


Figure 6. Typical Characteristics: I_F vs. V_F

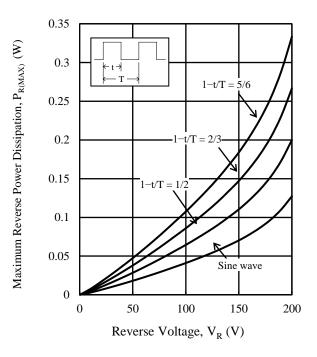


Figure 5. $P_{R(MAX)}$ vs. V_R ($T_J = 150$ °C)

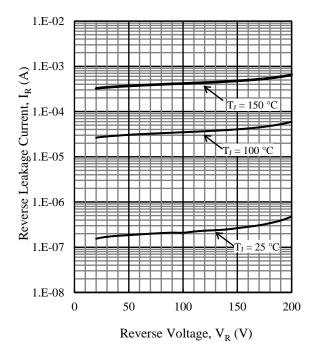


Figure 7. Typical Characteristics: I_R vs. V_R

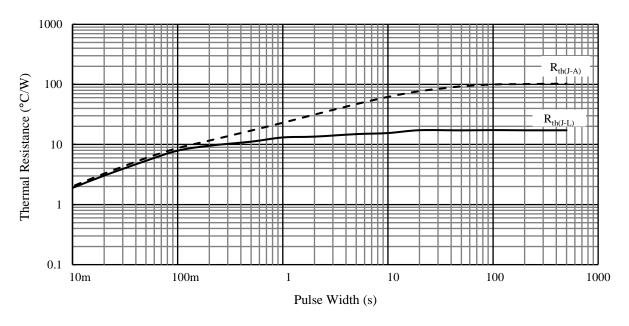
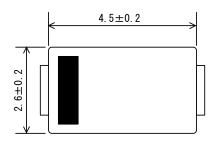
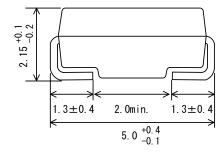


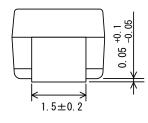
Figure 8. Typical Transient Thermal Resistance Characteristics

Physical Dimensions

• SJP Package







NOTES:

- Dimensions in millimeters
- Bare lead frame: Pb-free (RoHS compliant)
- Moisture Sensitivity Level 1 (MSL 1)
- When soldering the products, it is required to minimize the working time within the following limits:
- Flow: 260 °C / 10 s, 1 time

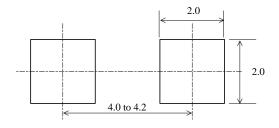
Reflow:

Preheat: $150 \, ^{\circ}\text{C}$ to $200 \, ^{\circ}\text{C} \, / \, 60 \, \text{s}$ to $120 \, \text{s}$

Solder heating: 255 $^{\circ}$ C / 30s, 3 times (260 $^{\circ}$ C peak)

Soldering Iron: 350 °C / 3.5 s, 1 time

• SJP Land Pattern Example



NOTE:

- Dimensions in millimeters

Marking Diagram

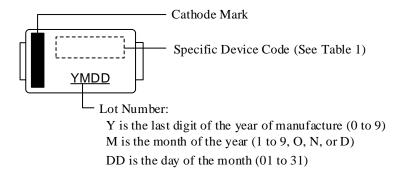


Table 1. Specific Device Code

Specific Device Code	Part Number
XF2	SJPX-F2

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